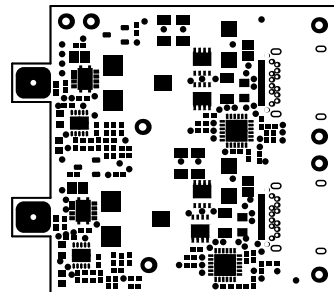
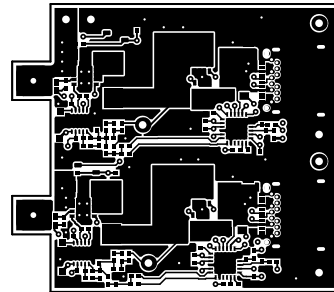


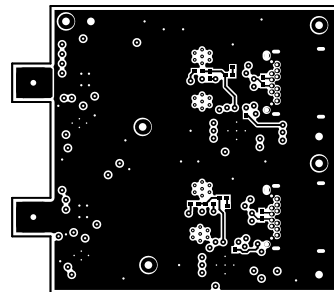
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 1/15/2017	10:02:44 AM	TEXAS INSTRUMENTS



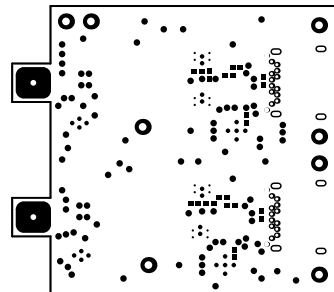
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 1/15/2017 10:02:45 AM	TEXAS INSTRUMENTS	



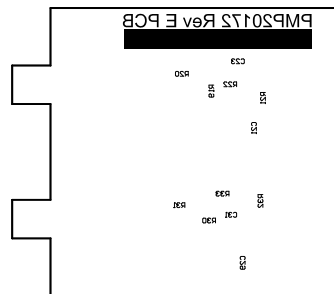
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 1/15/2017 10:02:46 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 1/15/2017 10:02:47 AM	TEXAS INSTRUMENTS	



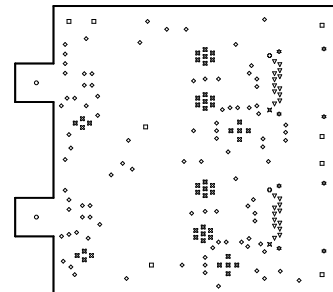
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 1/15/2017 10:02:48 AM	TEXAS INSTRUMENTS	



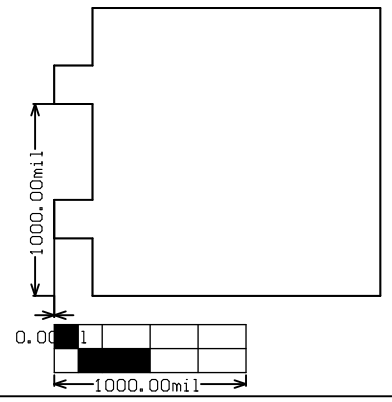
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 1/15/2017	10:02:49 AM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	2	25.59mil (0.650mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	46	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
◇	95	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
▽	24	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	25.59mil (0.650mm)	NPTH	Slot	Top Layer - Bottom Layer	
⊗	8	19.69mil (0.500mm)	PTH	Slot	Top Layer - Bottom Layer	
187 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 1/15/2017	10:02:50 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20172	REV: E	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 1/15/2017 10:02:51 AM	TEXAS INSTRUMENTS	

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